

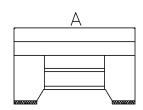
1、Features

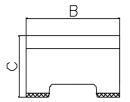
- Operating temperature -40°C~130°C
- Suitable for lead-free reflow soldering
- Compliance with RoHS and Halogen Free
- Bifilar winding
- AEC-Q200 qualified

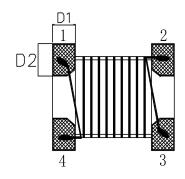
2. Application

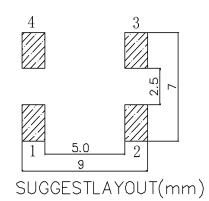
- Used radiation noise suppression for automotive CAN-BUS / Flex Ray systems
- Used for Industrial field bus systems

3、外形尺寸 SHAPES AND DIMENSIONS (Unit:mm)



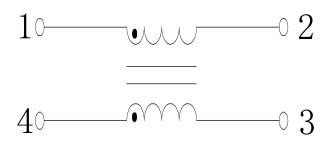






Series	А	В	С	D1	D2
8060F	8.0±0.2	6.6±0.2	4.0Max	1.5±0.1	2.0±0.1

4、电路图 Schematic Diagram





5、电性规格 Specification

Part Number	Inductance(uH) [100kHz/0.1V] 测量端 13,min	DC Resistance (Ω)Max. 测量端 13	Q 值 测量端 13 min	绝缘电阻(M Ω) 500V DC 测量端绕组~磁芯 min	耐电压 (VDC) ,1mA/3s 测量端绕组~绕组) min
AP8066F-301L	300	1.0	3	100	1000
AP8066F-401L	400	1.0	3	100	1000

6、焊接和安装 Soldering and Mounting

6-1. Soldering

Mildly activated rosin fluxes are preferred. FPE terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

6.2 Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

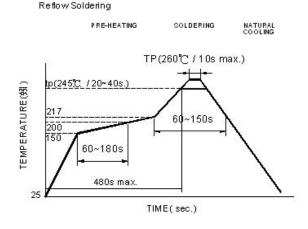
6.3 Soldering Iron(Figure 2):

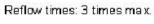
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

•Preheat circuit and products to 150°C •350°C tip temperature (max) ·Never contact the ceramic with the iron tip ·1.0mm tip diameter (max)

·Use a 20 watt soldering iron with tip diameter of 1.0mm

·Limit soldering time to 4~5 sec.







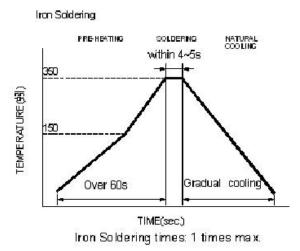


Fig.2

7、包装信息 Packaging Information

Series	Chip/Reel	Carton	
8066F	1000	10000	